

PENDING CLAIMS

Claims 1-41 (Cancelled)

42. (previously presented) An interconnect assembly for a microstructure comprising:

a base having first and second opposing surfaces, a cavity extending into said base from said first opposing surface, and a trench extending into said base from said first opposing surface, wherein said trench includes a distal end adjacent to said cavity; and  
a bond pad formed on a side wall of said cavity adjacent said trench.

43. (previously presented) The interconnect assembly of claim 42 wherein the base includes a lead formed in said trench and conductively coupled to the bond pad on the side wall of said cavity.

44. (previously presented) The interconnect assembly of claim 42 wherein the trench is etched in the base and the bond pad is formed in said etched trench.

45. (previously presented) The interconnect assembly of claim 42 wherein the bond pad includes a raised surface spaced from the side wall of said cavity.

46. (previously presented) The interconnect assembly of claim 42 wherein said cavity is etched and said bond pad is formed on the etched cavity wall.

47. (previously presented) The interconnect assembly of claim 42 wherein the base includes a base portion and a floating portion

movable relative to said base portion and said cavity is formed in the floating portion.

48. (previously presented) The interconnect assembly of claim 42 and further comprising the microstructure disposed in said cavity and the microstructure including at least one bond pad to interface with the bond pad formed on the side wall of said cavity.

49. (previously presented) The interconnect assembly of claim 42 wherein the side wall has a generally vertical orientation when the first and second opposing surfaces are orientated generally horizontally.

50. (previously presented) An electrical interconnect of a microstructure comprising:

- a frame having a cavity and a trench etched in said frame;
- an electrical lead deposited in said trench; and
- a bond pad embedded in a side wall of said cavity of said frame, said bond pad being electrically coupled to said electrical lead.

51. (previously presented) The electrical interconnect of claim 50 comprising a plurality of bond pads embedded in said side wall of said cavity.

52. (previously presented) The electrical interconnect of claim 50 and further comprising a microstructure body disposed in said cavity having a bond pad to interface with the bond pad on said side wall of said cavity.

53. (previously presented) The electrical interconnect of claim 52 wherein the microstructure body is a slider including at least one transducer element.

54. (previously presented) The electrical interconnect of claim 50 wherein the frame includes a base portion and a floating portion and said cavity is formed in the floating portion.

55. (previously presented) The electrical interconnect of claim 50 wherein the embedded bond pad is formed in a trench opened to said cavity.

56. (previously presented) An integrated interconnect assembly for a microstructure comprising:

a microstructure body including a microstructure cavity having a bond pad formed on an inner side wall of the microstructure cavity and conductively coupled to a lead embedded below an external surface of the microstructure body.

57. (previously presented) The integrated interconnect of claim 56 wherein the bond pad is formed on an etched cavity wall.

58. (previously presented) The integrated interconnect of claim 56 wherein the lead is formed in an etched trench on the microstructure body.

59. (previously presented) The integrated interconnect of claim 56 and comprising a slider disposed in said microstructure cavity having at least one bond pad.

60. (previously presented) The integrated interconnect of claim 56 wherein the microstructure body includes a floating portion and said microstructure cavity is formed in the floating portion.

61. (previously presented) The integrated interconnect of claim 56 wherein the bond pad is embedded below an etched surface of the inner side wall.